

MOS FIELD EFFECT TRANSISTOR 2SK3573

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3573 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

FEATURES

- 4.5 V drive available
- Low on-state resistance $R_{DS(on)1} = 4.0 \text{ m}\Omega$ MAX. (Vgs = 10 V, ID = 42 A)

• Low gate charge

 $Q_G = 68 \text{ nC TYP.}$ (VDD = 16 V, VGS = 10 V, ID = 83 A)

• Surface mount device available

★ ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3573	TO-220AB
2SK3573-S	TO-262
2SK3573-ZK	TO-263
2SK3573-Z	TO-220SMD Note

Note TO-220SMD package is produced only in Japan.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	20	V	
Gate to Source Voltage (Vps = 0 V)	Vgss	±20	V	
Drain Current (DC) (Tc = 25°C)	ID(DC)	±83	Α	
Drain Current (pulse) Note	D(pulse)	±332	Α	
Total Power Dissipation (T _A = 25°C)	P _{T1}	1.5	W	
Total Power Dissipation (Tc = 25°C)	P _{T2}	105	W	
Channel Temperature	Tch	150	°C	
Storage Temperature	Tstg	-55 to +150	°C	

Note PW \leq 10 μ s, Duty Cycle \leq 1%

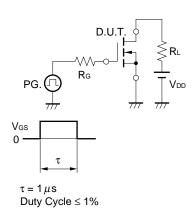
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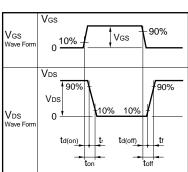


ELECTRICAL CHARACTERISTICS (TA = 25°C)

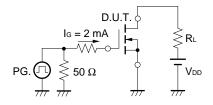
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ipss	V _{DS} = 20 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	lgss	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.5		2.5	V
Forward Transfer Admittance	yfs	V _{DS} = 10 V, I _D = 42 A	27			S
Drain to Source On-state Resistance	RDS(on)1	Vgs = 10 V, ID = 42 A		2.9	4.0	mΩ
	RDS(on)2	Vgs = 4.5 V, ID = 42 A		3.8	6.0	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		4000		pF
Output Capacitance	Coss	Vgs = 0 V		1550		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		570		pF
Turn-on Delay Time	t d(on)	V _{DD} = 10 V, I _D = 42 A		23		ns
Rise Time	t r	Vgs = 10 V		23		ns
Turn-off Delay Time	td(off)	R _G = 10 Ω		110		ns
Fall Time	t f			40		ns
Total Gate Charge	Q _G	VDD = 16 V		68		nC
Gate to Source Charge	Qgs	Vgs = 10 V		12		nC
Gate to Drain Charge	Q _{GD}	ID = 83 A		18		nC
Body Diode Forward Voltage	V _{F(S-D)}	IF = 83 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 83 A, VGS = 0 V		77		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		115		nC

TEST CIRCUIT 1 SWITCHING TIME



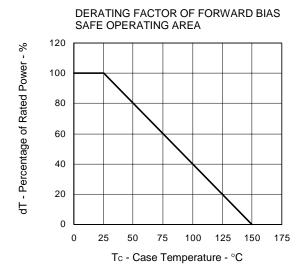


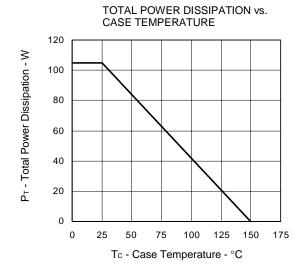
TEST CIRCUIT 2 GATE CHARGE



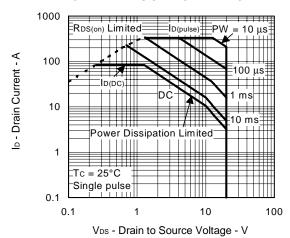


TYPICAL CHARACTERISTICS (TA = 25°C)

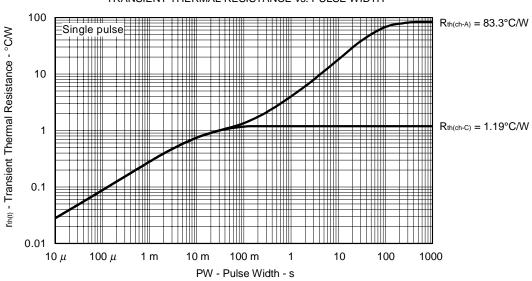




FORWARD BIAS SAFE OPERATING AREA

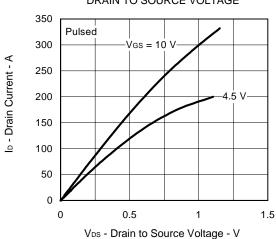


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

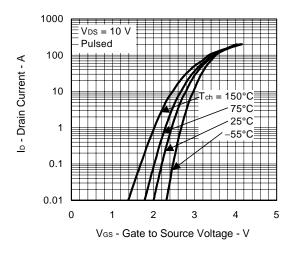


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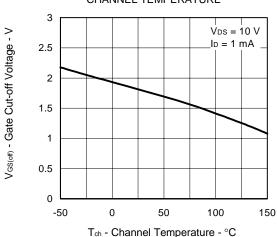
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



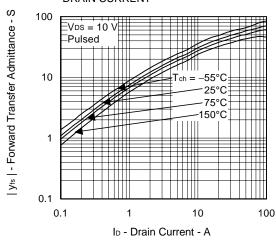
FORWARD TRANSFER CHARACTERISTICS



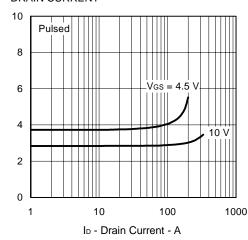
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



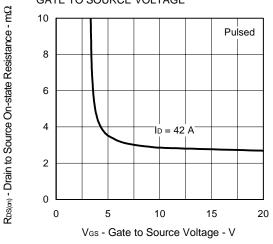
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



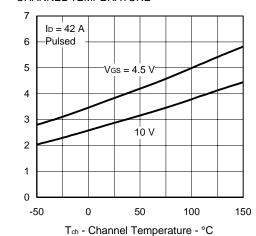
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



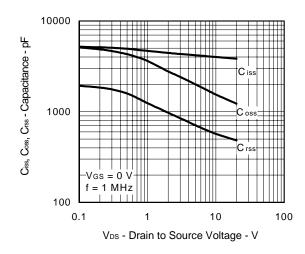
R_{DS(m)} - Drain to Source On-state Resistance - mΩ

NEC

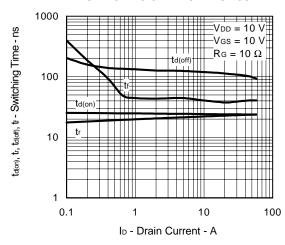
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



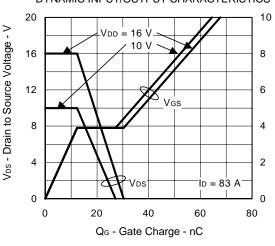
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



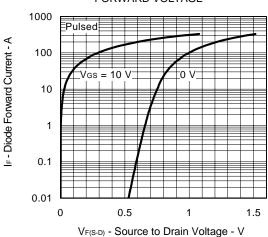
SWITCHING CHARACTERISTICS



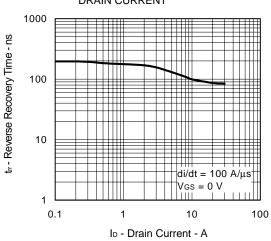
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



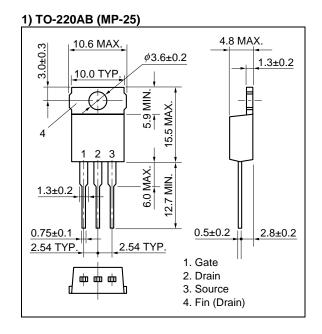
REVERSE RECOVERY TIME vs. DRAIN CURRENT

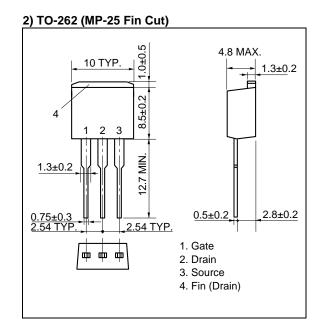


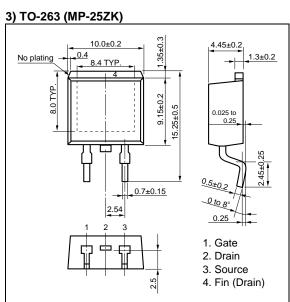
Ves - Gate to Source Voltage - V

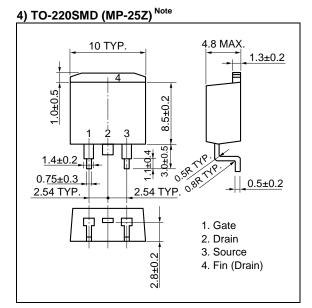


★ PACKAGE DRAWINGS (Unit: mm)



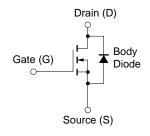






Note This package is produced only in Japan.

EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

[MEMO]

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